



STPR1020CB/CG/CT/CF/CFP

ULTRA-FAST RECOVERY RECTIFIER DIODES

MAIN PRODUCTS CHARACTERISTICS

I _{F(AV)}	2 x 5 A
V _{RRM}	200 V
T _j (max)	150°C
V _F (max)	0.99 V
trr (max)	30 ns

PRELIMINARY DATASHEET

FEATURES

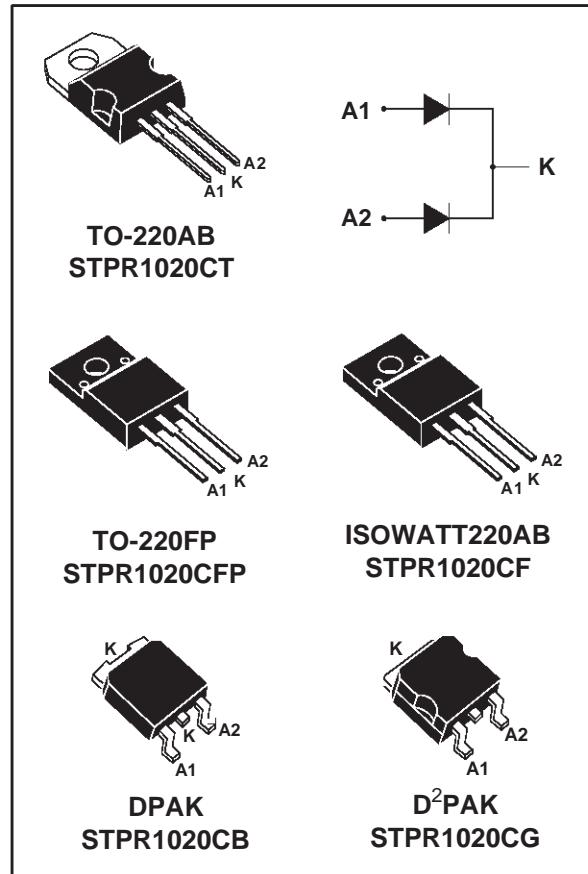
- SUITED FOR SMPS
- LOW LOSSES
- LOW FORWARD AND REVERSE RECOVERY TIME
- HIGH SURGE CURRENT CAPABILITY
- INSULATED PACKAGES: ISOWATT220AB / TO-220FP
Insulation Voltage = 2000V DC
Capacitance = 12 pF

DESCRIPTION

Dual center tap rectifier suited for Switched Mode Power Supplies and high frequency DC to DC converters.

Packaged in DPAK, D²PAK, TO-220AB, TO-220FP or ISOWATT220AB, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

ABSOLUTE MAXIMUM (limiting values, per diode)



Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			200	V
I _{F(RMS)}	RMS forward current			10	A
	D ² PAK / TO-220AB / ISOWATT220AB / TO-220FP			A	
I _{F(AV)}	Average forward current $\delta = 0.5$	DPAK	T _c =125°C	7	A
		D ² PAK / DPAK TO-220AB	T _c =115°C	Per diode	5
		ISOWATT220AB	T _c =110°C	Per device	10
I _{FSM}	Surge non repetitive forward current			10ms sinusoidal	A
T _{stg}	Storage temperature range			- 65 to + 150	°C

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THERMAL RESISTANCES

Symbol	Parameter			Value	Unit
$R_{th(j-c)}$	Junction to case	TO-220AB / D ² PAK / DPAK	Per diode	4.0	°C/W
			Total	2.4	
		ISOWATT220AB	Per diode	6.0	
			Total	4.0	
	TO-220FP	Per diode	6.5		
			Total	5	
$R_{th(c)}$	Coupling	TO-220AB / D ² PAK / DPAK			0.7
		ISOWATT220AB			2.0
		TO-220FP			3.5

When diodes 1 and 2 are used simultaneously :

$$\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)} (\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameters	Test conditions		Min.	Typ.	Max.	Unit
I_R *	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			50	μA
		$T_j = 100^\circ\text{C}$				0.6	mA
V_F **	Forward voltage drop	$T_j = 125^\circ\text{C}$	$I_F = 5 \text{ A}$		0.8	0.99	V
		$T_j = 125^\circ\text{C}$	$I_F = 10 \text{ A}$		0.95	1.20	
		$T_j = 25^\circ\text{C}$	$I_F = 10 \text{ A}$			1.25	

Pulse test : * $t_p = 5 \text{ ms}, \delta < 2 \%$

** $t_p = 380 \mu\text{s}, \delta < 2 \%$

To evaluate the conduction losses use the following equation :

$$P = 0.78 \times I_F(\text{AV}) + 0.042 \times I_F^2(\text{RMS})$$

RECOVERY CHARACTERISTICS

Symbol	Test conditions			Min.	Typ.	Max.	Unit
trr	$T_j = 25^\circ\text{C}$	$I_F = 0.5\text{A}$	$I_{RR} = 0.25\text{A}$			30	ns
tfr	$T_j = 25^\circ\text{C}$	$I_F = 1\text{A}$	$dI_F/dt = 50 \text{ A}/\mu\text{s}$		20		ns
V_{FP}	$T_j = 25^\circ\text{C}$	$I_F = 1\text{A}$	$dI_F/dt = 50 \text{ A}/\mu\text{s}$		3		V

Fig. 1: Average forward power dissipation versus average forward current (per diode).

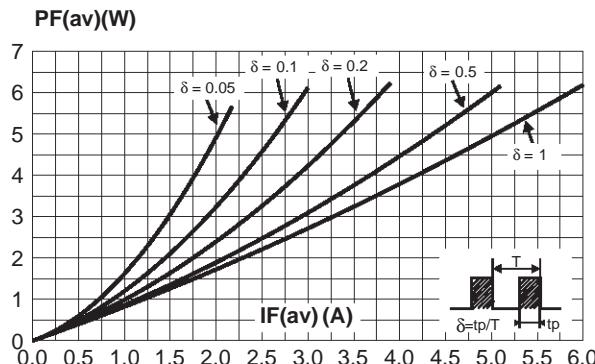


Fig. 2: Peak current versus form factor (per diode).

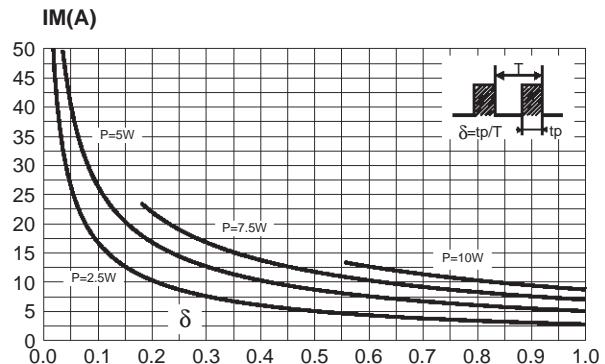


Fig. 3-1: Average forward current versus ambient temperature ($\delta = 0.5$, TO-220AB, DPAK, D²PAK).

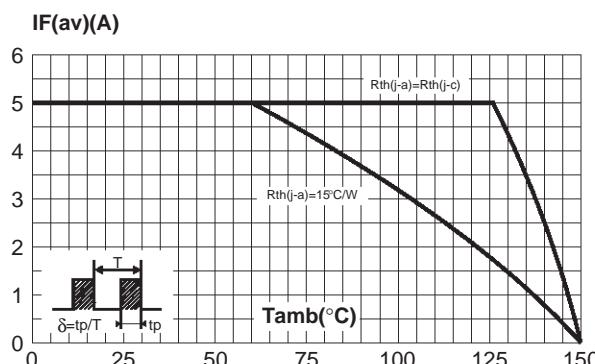


Fig. 3-2: Average forward current versus ambient temperature ($\delta = 0.5$, ISOWATT220AB, TO-220FP).

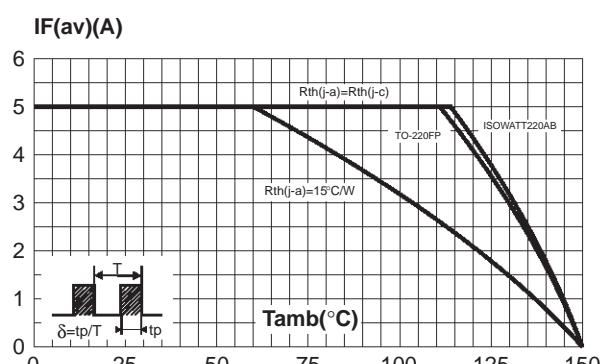


Fig. 4-1: Non repetitive surge peak forward current versus overload duration (TO-220AB, DPAK, D²PAK).

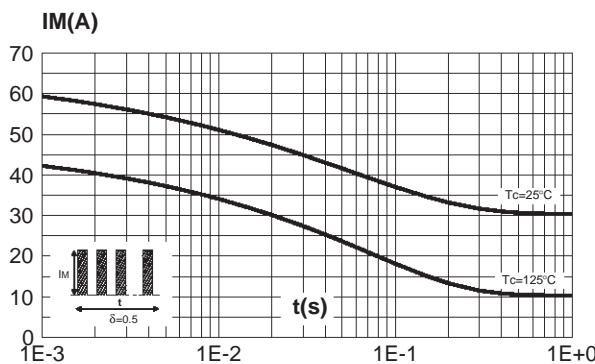
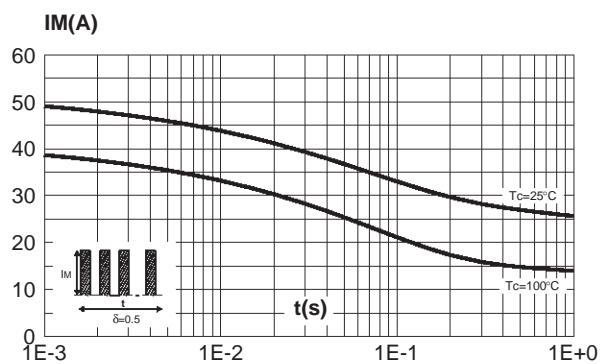


Fig. 4-2: Non repetitive surge peak forward current versus overload duration (ISOWATT220AB).



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Fig. 4-3: Non repetitive surge peak forward current versus overload duration (TO-220FP).

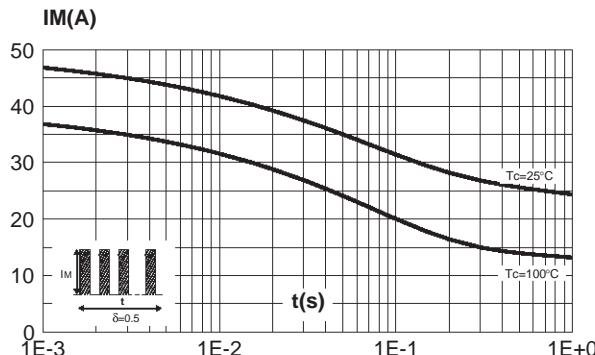


Fig. 5-2: Relative variation of thermal impedance junction to case versus pulse duration (ISOWATT220AB, TO-220FP).

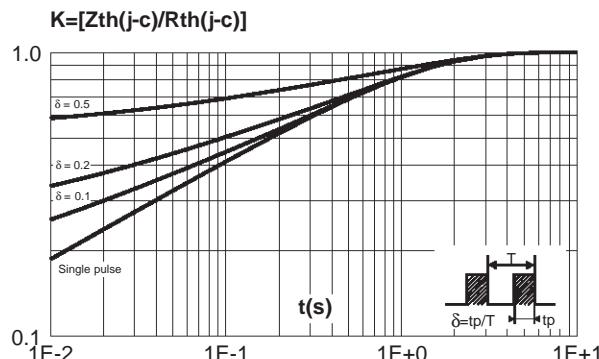


Fig. 7: Junction capacitance versus reverse voltage applied (typical values, per diode).

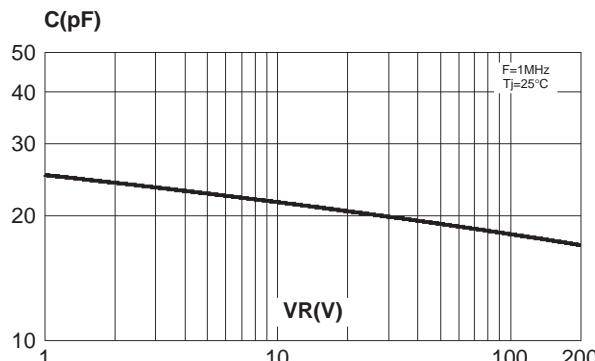


Fig. 5-1: Relative variation of thermal impedance junction to case versus pulse duration ($D^2\text{PAK}$, DPAK , TO-220AB).

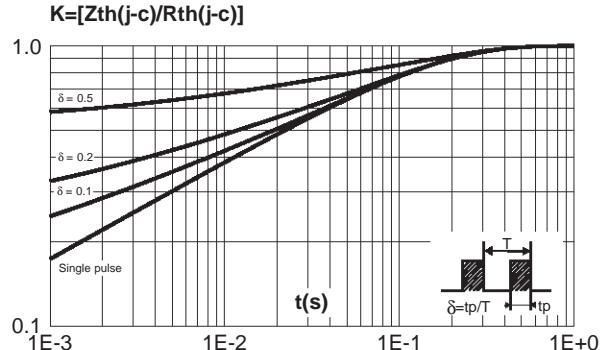


Fig. 6: Forward voltage drop versus forward current (maximum values, per diode).

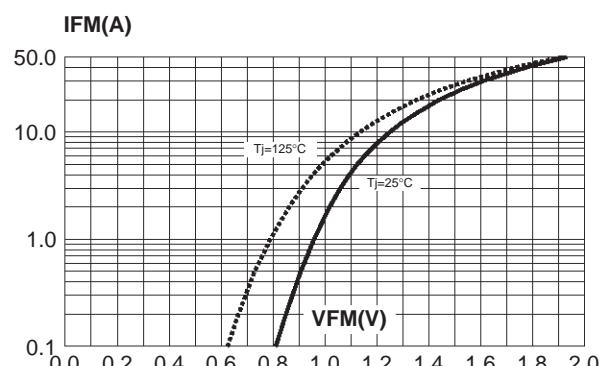


Fig. 8: Reverse recovery charges versus dI/dt (per diode).

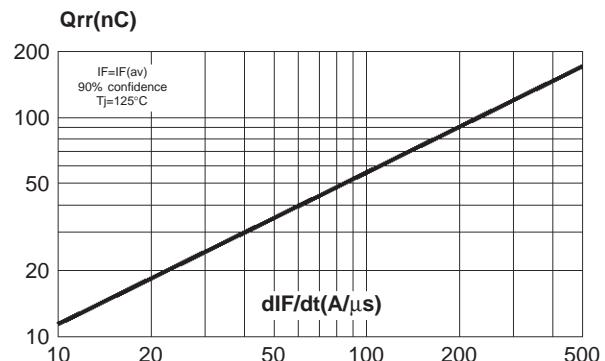


Fig. 9: Peak reverse recovery current versus dIF/dt (per diode).

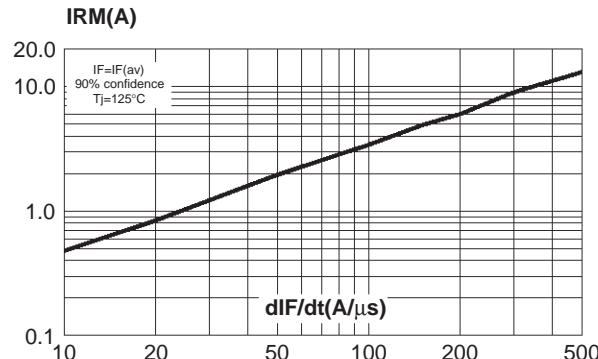


Fig. 10: Dynamic parameters versus junction temperature (per diode).

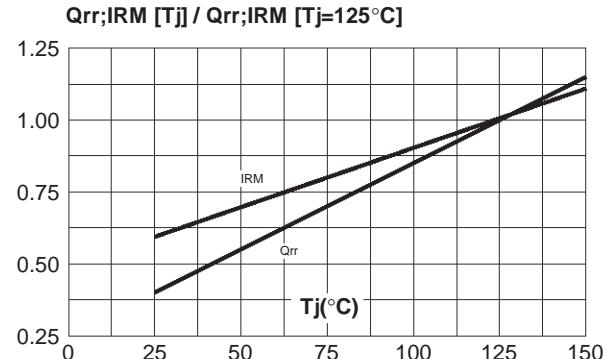
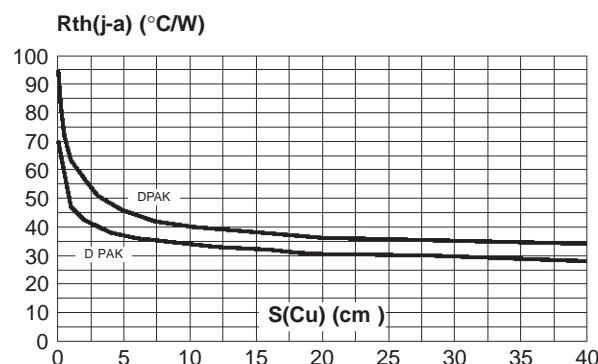


Fig. 11: Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness: 35 μm).

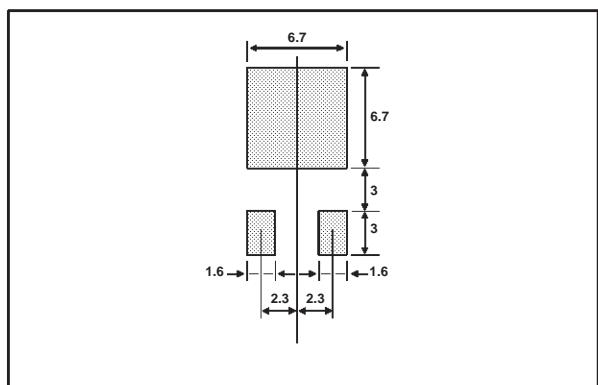


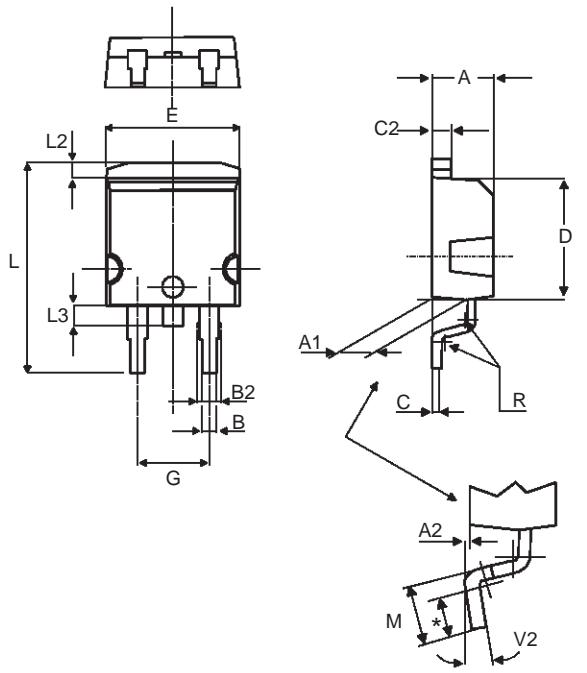
STPR1020CB/CG/CT/CF/CFP

PACKAGE MECHANICAL DATA DPAK

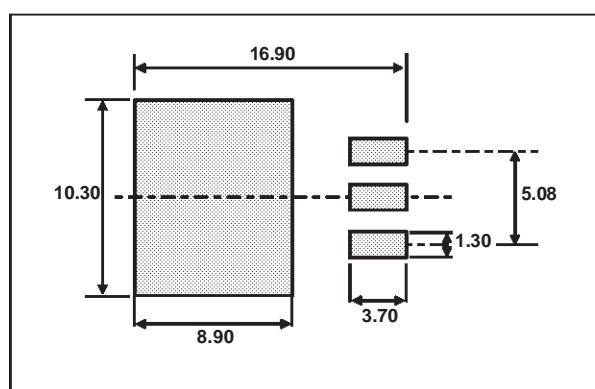
REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
V2	0°	8°	0°	8°

FOOT PRINT (in millimeters) DPAK



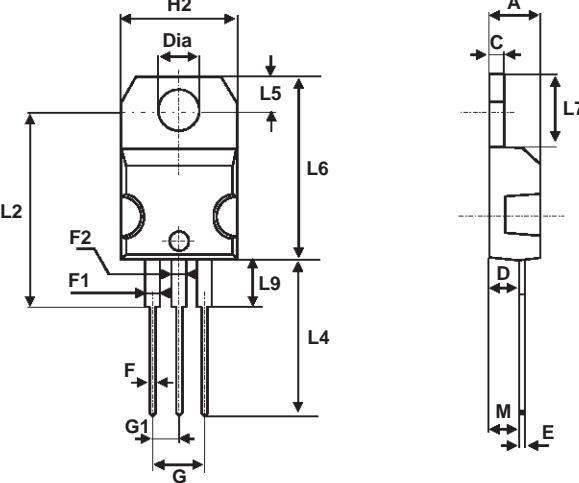
PACKAGE MECHANICAL DATA
D²PAK


REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

FOOT PRINT (in millimeters)
D²PAK


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PACKAGE MECHANICAL DATA TO-220AB (JEDEC compatible)



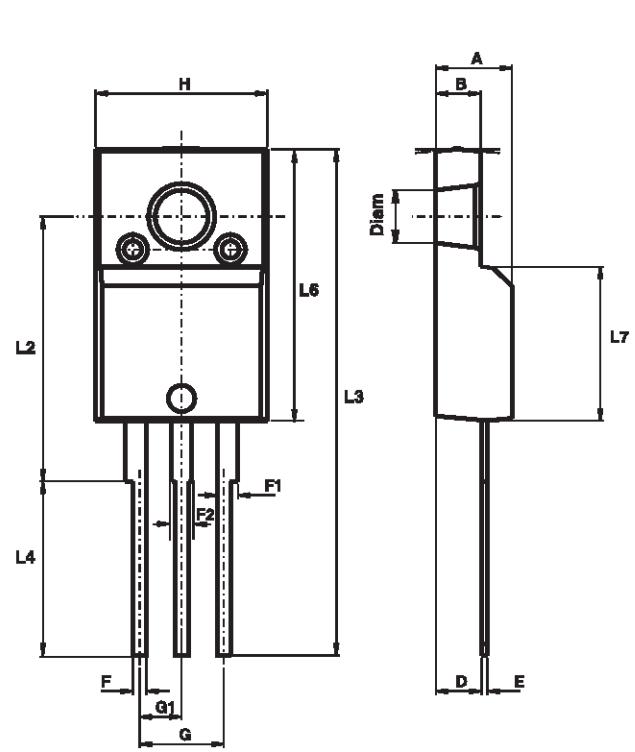
REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
F2	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
G1	2.40	2.70	0.094	0.106
H2	10	10.40	0.393	0.409
L2	16.4 typ.		0.645 typ.	
L4	13	14	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam.	3.75	3.85	0.147	0.151

STPR1020CB/CG/CT/CF/CFP**PACKAGE MECHANICAL DATA**

TO-220FP

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.9	0.173	0.193
B	2.5	2.9	0.098	0.114
D	2.45	2.75	0.096	0.108
E	0.40	0.70	0.015	0.027
F	0.60	1	0.023	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.204
G1	2.40	2.70	0.094	0.106
H	10	10.7	0.393	0.421
L2	16 Typ.		0.63 Typ.	
L3	28.6	30.6	1.126	1.204
L4	9.8	10.7	0.385	0.421
L6	15.8	16.4	0.622	0.645
L7	9.00	9.90	0.354	0.389
Dia.	2.90	3.50	0.114	0.137

PACKAGE MECHANICAL DATA
 ISOWATT220AB (JEDEC compatible)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
B	2.50	2.70	0.098	0.106
D	2.50	2.75	0.098	0.108
E	0.40	0.70	0.016	0.028
F	0.75	1.00	0.030	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.40	2.70	0.094	0.106
H	10.00	10.40	0.394	0.409
L2	16.00 typ.		0.630 typ.	
L3	28.60	30.60	1.125	1.205
L4	9.80	10.60	0.386	0.417
L6	15.90	16.40	0.626	0.646
L7	9.00	9.30	0.354	0.366
Diam	3.00	3.20	0.118	0.126

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPR1020CB	STPR1020CB	DPAK	0.3g	75	Tube
STPR1020CB-TR	STPR1020CB	DPAK	0.3g	2500	Tape & reel
STPR1020CT	STPR1020CT	TO-220AB	2.23g	50	Tube
STPR1020CF	STPR1020CF	ISOWATT220AB	2.2g	50	Tube
STPR1020CG	STPR1020CG	D ² PAK	1.48g	50	Tube
STPR1020CFP	STPR1020CFP	TO-220FP	2.0g	50	Tube

- Cooling method : by conduction (C)
- Recommended torque value (ISOWATT220AB, TO-220FP): 0.55 N.m.
- Maximum torque value (ISOWATT220AB, TO-220FP): 0.70 N.m.
- Recommended torque value (TO-220AB): 0.8 N.m
- Maximum torque value (TO-220AB): 1.0 N.m.
- Epoxy meets UL94,V0

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